

Low Pressure Molding Application 低壓成型應用



Magnetic Switch
磁性開關



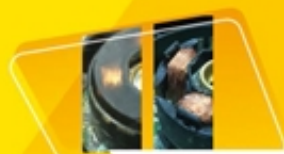
Micro Switch
微動開關



Proximity Switch
近接開關



Rocker Switch
搖臂開關



Fan Motor sealing
風扇馬達封裝



Reed Switch
磁簧開關



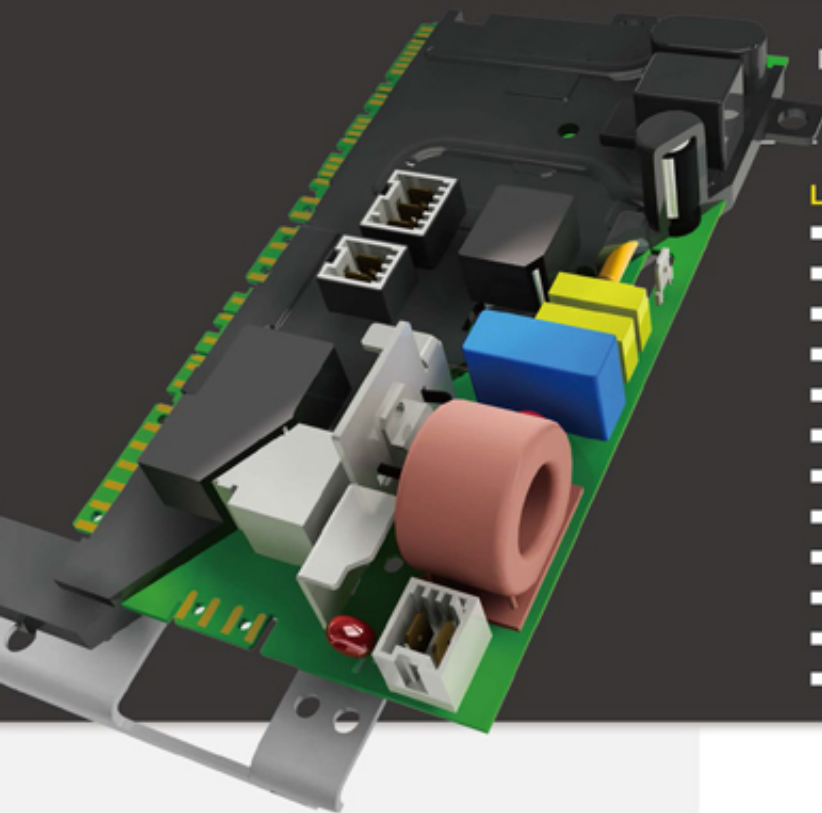
Water-Proof Connector
防水連接器



PCB Water-Resistance sealing
電路板防水封裝

低壓成型技術

Low Pressure Molding Technology



Eco-friendly new process to replace potting and sealing
環保新製程取代灌膠封裝

Low pressure molding advantages :

- Insulation
- Temperature resistance
- Dust-proof
- Waterproof
- Moisture-proof
- Flame retardant
- Impact resistance
- Vibration reduction
- Well Bonding
- Reduce costs
- Shorter cycle time
- Resistance to chemical corrosion

低壓製程優點 :

- 絕緣
- 耐溫
- 防塵
- 防水
- 防潮
- 阻燃
- 抗衝擊
- 減振
- 結合力好
- 降低成本
- 成型週期短
- 耐化學腐蝕

Potting 10sec
注膠10秒

Cooling process (20sec)
冷卻20秒取出

Defoaming /aging process Several hours
消泡/熟化/固化 數小時

VS.

Insert(5sec)
埋件5秒

Cooling(20sec)
冷卻20秒

Productivity Increase
提高產能

Injection/ pressure holding(20sec)
射出保壓20秒

Ejection (3sec.)
頂出脫模3秒

NEW

低壓
成型
Low
Pressure
Molding

30*60*25 (W*D*H)

Estimated weight: 10~20g/pc

1. Lighter product
2. Cover all kinds of shapes

預估低壓料所需重量：10~20g/pc (密度=1)

1. 產品輕量化
 2. 可以適用各種形狀結構
- 外殼：不是每一產品都有需要

灌膠
製程
Potting

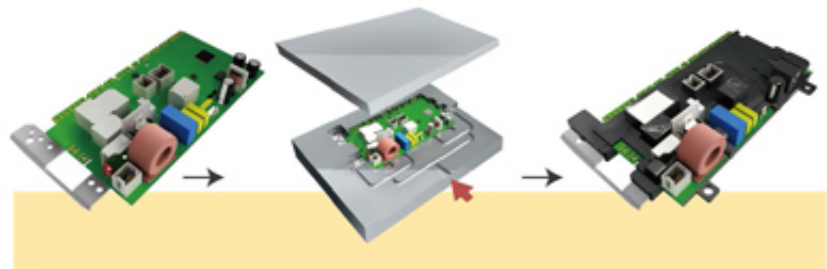
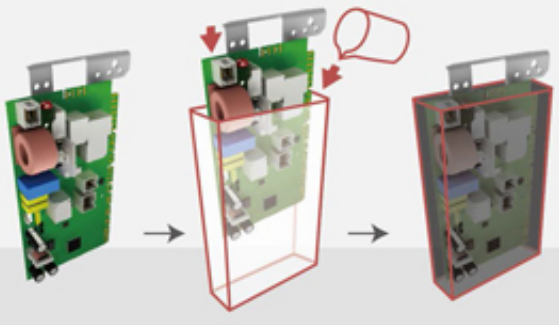
36*60*25(W*D*H)

Estimated weight : 60~90g/pc

EPOXY or Silicon

(Density=1.3~1.7g/cm³)

預估灌膠所需重量：60~90g/pc
EPOXY /Silicon 密度 1.3~1.7g/cm³



鑫野智動工業股份有限公司 KING'S Solution Corp.

33392 桃園市龜山區南上路457號 | No.457, Nanshang Rd., Guishan Dist, Taoyuan City 33392, Taiwan | www.injection.com.tw/
| sales@kingsmachinery.com.tw | Tel : +886-3-3218768 | Fax : +886-3-3218769

廣東省惠州市陳江鎮梧村寶鑫工業區 | Bao Xin Industrial Park, Wu Village ,Chen Jiang Town, Hui Zhou City Guangdong

